

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|--------|--|---|------------------|---------|------------------|
| L1 | 2 | "20050046003" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/26 21:31 |
| L2 | 592819 | (stack stacking stacked stackable mount mounting mounted mountable) with (semiconductor die chip ic (integrated adj circuit) component dice) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/26 22:18 |
| L3 | 769677 | (opening via hole gap space) with (carrier board substrate pcb ((printed wiring circuit) adj3 board)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/26 21:35 |
| L4 | 2 | 1 and 2 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/26 21:35 |
| L5 | 108403 | 3 and 2 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/26 21:36 |
| L6 | 191177 | (encapsulation encapsulated encapsulating encasulate encase resin epoxy encapsulant) with (exposing expose exposed open opening cavity) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/26 22:22 |
| L7 | 24842 | 6 and (heat with (dissipate dissipating dissipation dissipated sink radiate radiating radiated metal thermal block blocking)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/26 22:22 |
| L8 | 46816 | 2 same 3 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/26 21:40 |

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|-----|--------|---|---|----|----|------------------|
| L9 | 1508 | 6 same 8 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/26 21:41 |
| L10 | 145 | 9 same (heat with (dissipate dissipating dissipation dissipated sink radiate radiating radiated metal thermal block blocking)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/26 22:07 |
| L11 | 1363 | 9 not 10 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/26 22:07 |
| L12 | 579543 | (stack stacking stacked stackable mount mounting mounted mountable) with (diode led emiconductor die chip ic (integrated adj circuit) component dice) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/26 22:19 |
| L13 | 46816 | 2 same 3 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/26 22:19 |
| L14 | 3911 | 13 same (heat with (dissipate dissipating dissipation dissipated sink radiate radiating radiated metal thermal block blocking)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/26 22:19 |
| L15 | 145 | 14 same 6 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/26 22:21 |
| L16 | 0 | 15 not 10 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/26 22:21 |

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| L17 | 21080 | 12 and 6 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/26 22:22 |
| L18 | 9766 | 3 and 17 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/26 22:22 |
| L19 | 3864 | 18 and (heat with (dissipate dissipating dissipation dissipated sink radiate radiating radiated metal thermal block blocking)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/26 22:23 |
| L20 | 3531 | 19 not 11 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/26 22:23 |
| L21 | 2628 | wire and 20 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/26 22:23 |
| L22 | 314 | lens and 21 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/26 22:24 |
| L23 | 1 | "6521881".PN. | USPAT; USOCR | OR | OFF | 2005/06/26 22:40 |
| L24 | 1 | "6680525".PN. | USPAT; USOCR | OR | OFF | 2005/06/26 22:40 |
| L25 | 1 | "20020173071".PN. | US-PGPUB | OR | OFF | 2005/06/26 22:41 |
| L26 | 1 | "6590269".PN. | USPAT; USOCR | OR | OFF | 2005/06/26 22:41 |
| L27 | 1 | "6531341".PN. | USPAT; USOCR | OR | OFF | 2005/06/26 22:41 |
| L28 | 1 | "6455774".PN. | USPAT; USOCR | OR | OFF | 2005/06/26 22:41 |
| L29 | 1 | "6396116".PN. | USPAT; USOCR | OR | OFF | 2005/06/26 22:42 |